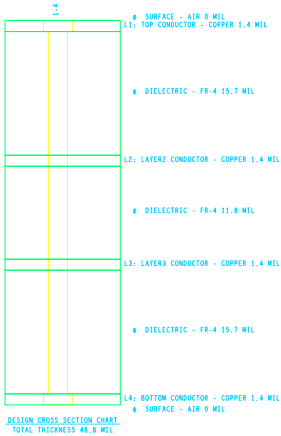
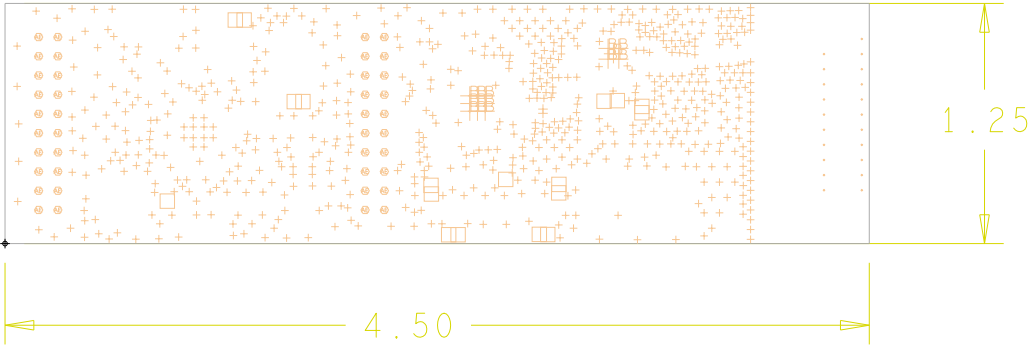


FAB NOTES:
1. ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
2. ALL DIMENSIONS SHALL BE TO THE CENTER OF THE HOLE UNLESS OTHERWISE NOTED.
3. BOARD MATERIAL SHALL BE 10/10/40 501 SOLA FR-3700R OR EQUIVALENT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
4. BOARD MATERIAL SHALL BE 10/10/40 501 SOLA FR-3700R OR EQUIVALENT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
5. OVERALL BOARD THICKNESS TO BE .040" +/- .005" AND APPLIED AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
6. MAX. WIP & WIP IN SET NOTS PER INCH.
7. BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-256 NETLIST.
8. 28 MIL TRACES ON LAYER 1 ARE 50 OHMS +/-10%, THEY ARE REFERENCE TO LAYER 2 GROUND.

PROCESS NOTES:
1. APPLY LPT1 SOLDERMASK OVER BARE COPPER (SMORC). SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV. COLOR OF MASK TO BE RED.
2. PLATE ALL EXPOSED AREAS WITH ELECTROLYTIC NICKEL. IMMERSION GOLD. NICKEL 100 MICRO INCHES MIN. MINIMUM 100 MICRO INCHES MIN.
3. SOLDERMASK ARTWORK HAS ZERO (0) OVERLAP PASS. FABRICATION TOLERANCE IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
4. APPLY NON-CONDUCTIVE LPT1 SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.
5. ALL VIAS ARE TENTED



DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILS					
FIGURE	SIZE	TOLERANCE	PLATED	QTY	
+	8.0	+3.0/-3.0	PLATED	2	
+	10.0	+3.0/-3.0	PLATED	672	
⊢	15.0	+3.0/-3.0	PLATED	14	
.	15.75	+3.0/-3.0	PLATED	21	
+	20.0	+3.0/-3.0	PLATED	1	
□	20.0	+3.0/-3.0	PLATED	8	
□	30.0	+3.0/-3.0	PLATED	10	
⊙	41.34	+3.0/-3.0	PLATED	40	



CUSTOMER: Texas Instruments			
BOARD NAME: BO0STXL-CC120-90		LAYER DESCRIPTION: Fabrication Drawing	
PROJECT NUMBER: XXXXXX	BOARD REV: A	RELEASE DATE: 2015-10-19	SHEET NUMBER: 1 of 1